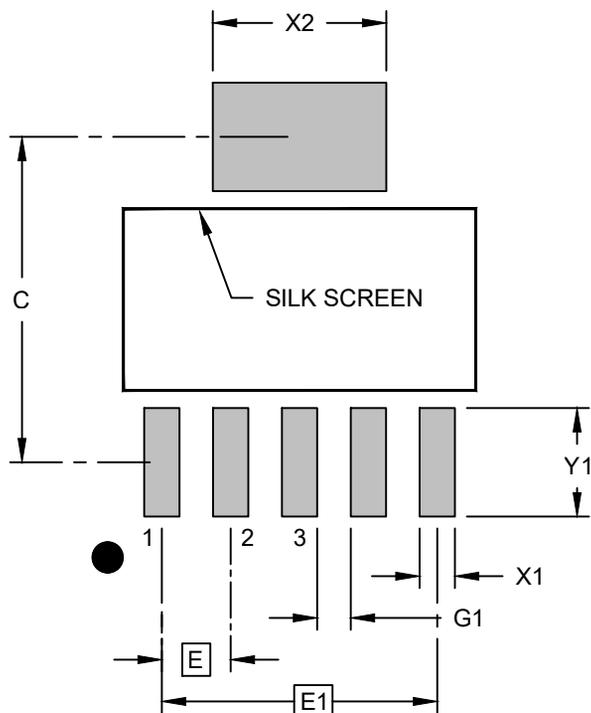


5-Lead Plastic Small Outline Transistor (N7X) [SOT-223]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pitch	E1	5.08 BSC		
Contact Pad Spacing	C	6.10		
Contact Pad Width (X5)	X1			0.65
Contact Pad Width	X2			3.20
Contact Pad Length (X6)	Y1			1.90
Distance Between Pads (X4)	G1	0.62		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during the reflow process.